



Product Change Notification: BLAS-01LHKC373

Date:

06-Oct-2025

Product Category:

Memory

Notification Subject:

CCB 7235.001 Final Notice: Qualification of AMK-EP27 as an additional die attach material, AMK-MC27 as an additional molding compound material and CuPdAu as an additional wire material for AT25M01-SSHM-T and AT25M01-SSHM-B catalog part numbers (CPN) available in 8L SOIC (.150in) package.

Affected CPNs:

[BLAS-01LHKC373_Affected_CPN_10062025.pdf](#)

[BLAS-01LHKC373_Affected_CPN_10062025.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of AMK-EP27 as an additional die attach material, AMK-MC27 as an additional molding compound material and CuPdAu as an additional wire material for AT25M01-SSHM-T and AT25M01-SSHM-B catalog part numbers (CPN) available in 8L SOIC (.150in) package.

Pre and Post Summary Changes:

	Pre Change	Post Change	
Assembly Site	Amkor Technology Philippine (P1/P2), INC. (ANAP)	Amkor Technology Philippine (P1/P2), INC. (ANAP)	
Wire Material	PdCu	PdCu	CuPdAu

Die Attach Material	8290 (PFAS)	8290 (PFAS)	AMK-EP27 (PFAS-free)
Molding Compound Material	G700A	G700A	AMK-MC27
Lead-Frame Material	C194	C194	C19400FH
DAP Surface Prep	PPF	PPF	Ring Ag

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying 66.9k wafer technology with AMK-EP27 as a new die attach material and CuPdAu as a new wire material.

Change Implementation Status: In Progress

Estimated First Ship Date: 24 December 2025 (date code: 2552)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	October 2025					>	December 2025				
Work Week	40	41	42	43	44		49	50	51	52	01
Qual Report Availability		x									
Final PCN Issue Date		x									
Estimated Implementation Date										x	

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: October 07, 2025: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_BLAS-01LHKC373 Qual Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.